

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	170	takizawa-m\$.in.	USPAT	OR	OFF	2006/01/20 13:32
L2	211	takizawa-m\$.in.	US-PGPUB; USPAT	OR	OFF	2006/01/20 13:39
L3	2777	156/345.55 134/113 134/1.3 134/1.3 134/94.1 156/95.1	US-PGPUB; USPAT	OR	OFF	2006/01/20 13:40
L4	621	3 and (chang\$3 var\$4 differ\$4) with (rate\$1 speed\$1 velocit\$3)	US-PGPUB; USPAT	OR	OFF	2006/01/20 14:35
L5	507	4 and (wafer\$1 semiconductor\$1 substrate\$1)	US-PGPUB; USPAT	OR	OFF	2006/01/20 13:43
L6	227	3 and (chang\$3 var\$4 differ\$4) with (rate\$1 speed\$1 velocit\$3) with (etch\$3 dissolv\$3 clean\$3 rins\$3)	US-PGPUB; USPAT	OR	OFF	2006/01/20 14:23
L7	2177	("edge bead" "edge hump")	US-PGPUB; USPAT	OR	OFF	2006/01/20 14:24
L8	594	("edge bead" "edge hump") with (remov\$3 etch\$3 clean\$3)	US-PGPUB; USPAT	OR	OFF	2006/01/20 14:24
L9	175	8 and (chang\$3 var\$4 differ\$4) with (rate\$1 speed\$1 velocit\$3)	US-PGPUB; USPAT	OR	OFF	2006/01/20 14:25
L10	163	3 and (chang\$3 var\$4 differ\$4) with (ratio\$1)	US-PGPUB; USPAT	OR	OFF	2006/01/20 14:35
L11	191	3 and (chang\$3 var\$4 differ\$4 adjust\$4) with (ratio\$1)	US-PGPUB; USPAT	OR	OFF	2006/01/20 14:42
L12	93	11 not (2 4 5 6)	US-PGPUB; USPAT	OR	OFF	2006/01/20 14:36
L13	693	3 and (chang\$3 var\$4 differ\$4 adjust\$4) with (mix\$4 concentration composition)	US-PGPUB; USPAT	OR	OFF	2006/01/20 14:43
L14	575	13 not 11	US-PGPUB; USPAT	OR	OFF	2006/01/20 14:43
L15	455	14 and (wafer semiconductor)	US-PGPUB; USPAT	OR	OFF	2006/01/20 14:43